

PHOTOCOUPLER

PS8502, PS8502L1, PS8502L2, PS8502L3

HIGH SPEED ANALOG OUTPUT TYPE

8 mm CREEPAGE 8-PIN PHOTOCOUPLER

—NEPOC Series—

DESCRIPTION

The PS8502, PS8502L1, PS8502L2 and PS8502L3 are 8-pin high speed photocouplers containing a GaAlAs LED on input side and a PN photodiode and a high speed amplifier transistor on output side on one chip. The PS8502 is in a plastic DIP (Dual In-line Package) with 8 mm creepage distance product.

The PS8502L1 is lead bending type for long creepage distance.

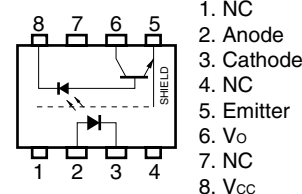
The PS8502L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

The PS8502L3 is lead bending type (Gull-wing) for surface mounting.

FEATURES

- Long creepage distance (8 mm MIN.: PS8502L1, PS8502L2)
- High common mode transient immunity (CM_H , $CM_L = \pm 15 \text{ kV}/\mu\text{s}$ MIN.)
- High supply voltage ($V_{CC} = 35 \text{ V}$ MAX.)
- High speed response (t_{PHL} , $t_{PLH} = 0.8 \mu\text{s}$ MAX.)
- High isolation voltage ($BV = 5\,000 \text{ V r.m.s.}$)
- TTL, CMOS compatible with a resistor
- Ordering number of tape product: PS8502L2-E3: 1 000 pcs/reel
: PS8502L3-E3: 1 000 pcs/reel
- Pb-Free product
- Safety standards
 - UL approved: File No. E72422
 - CSA approved: No. CA 101391
 - BSI approved: No. 8937, 8938
 - SEMKO approved: No. 615433
 - NEMKO approved: No. P06207243
 - DEMKO approved: No. 314091
 - FIMKO approved: No. FI 22827
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

PIN CONNECTION
(Top View)



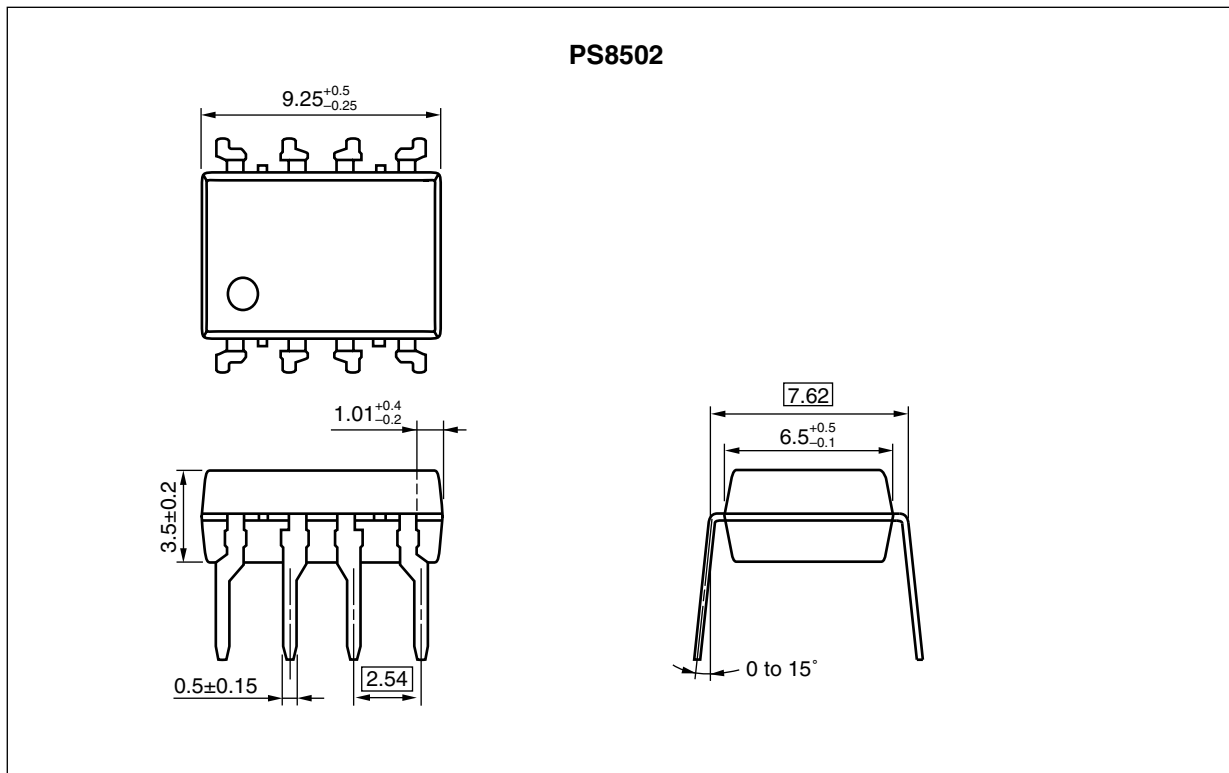
APPLICATIONS

- Interface for measurement or control equipment
- Substitutions for relays and pulse transformers
- Modem, communications device
- General purpose inverter

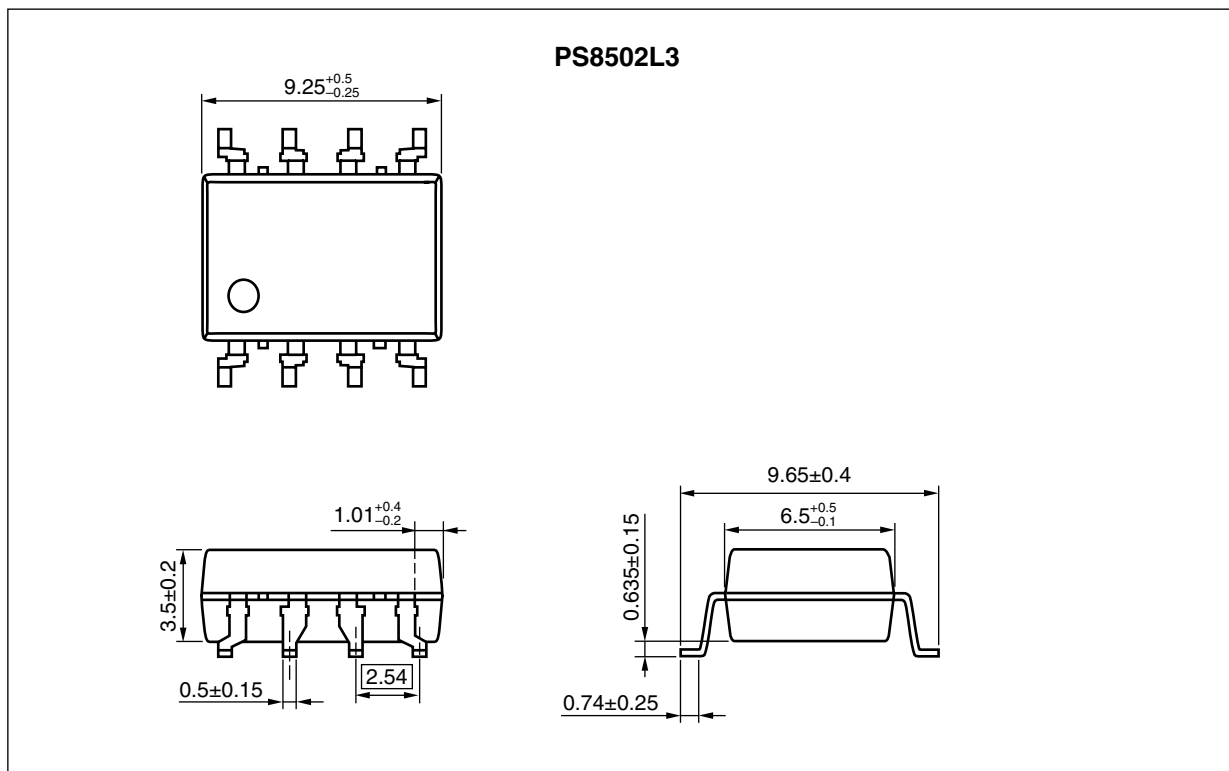
The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

PACKAGE DIMENSIONS (UNIT: mm)

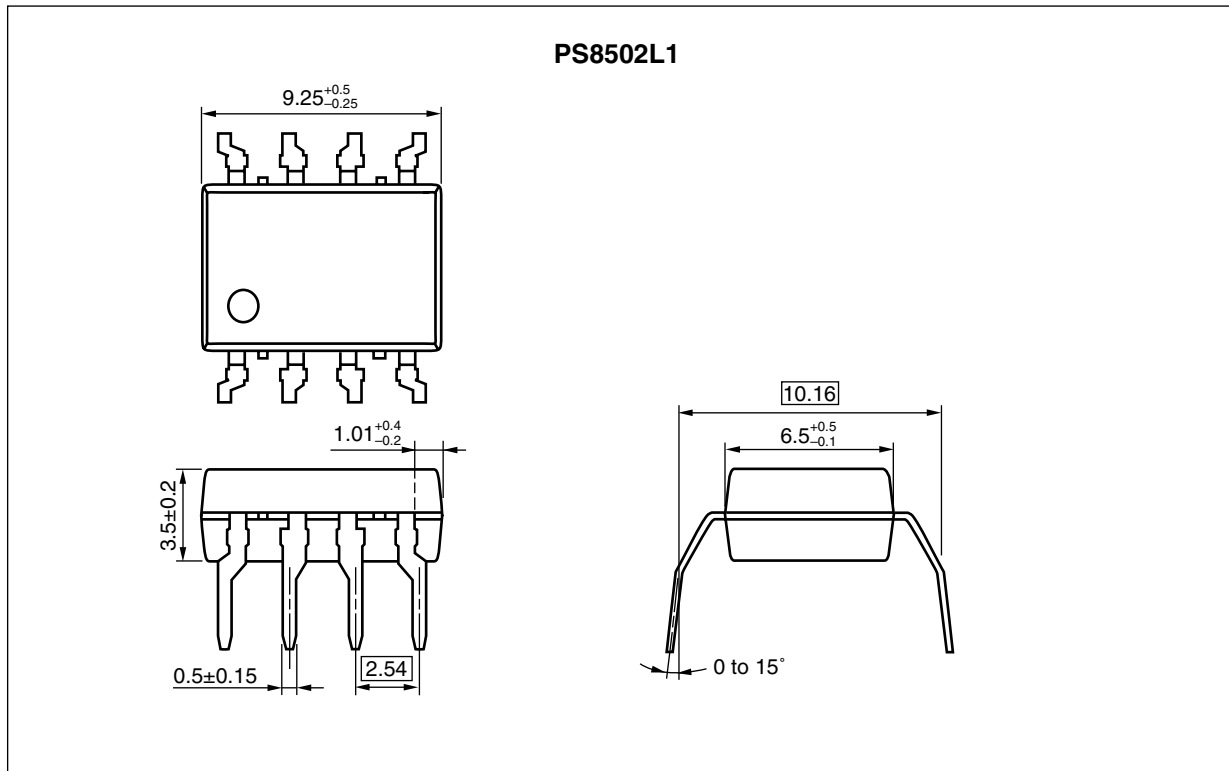
DIP Type



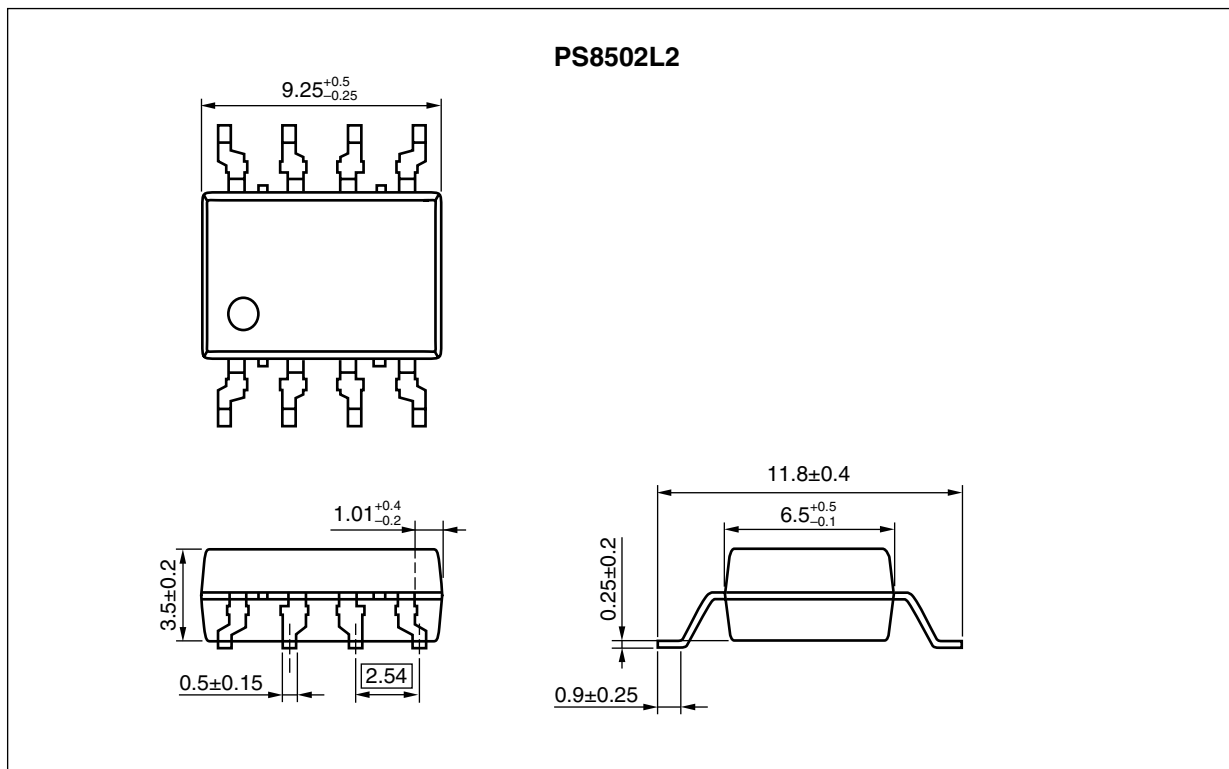
Lead Bending Type (Gull-wing) For Surface Mount



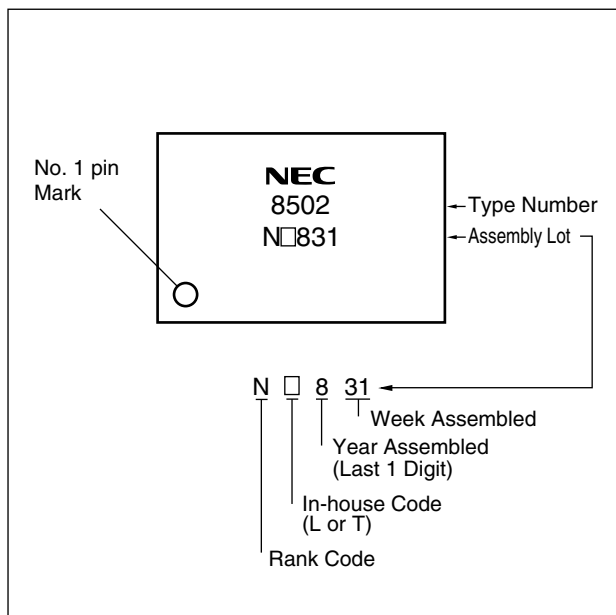
Lead Bending Type For Long Creepage Distance



Lead Bending Type For Long Creepage Distance (Gull-wing) For Surface Mount



<R> MARKING EXAMPLE



PHOTOCOUPLER CONSTRUCTION

Parameter	PS8502, PS8502L3	PS8502L1, PS8502L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number* ¹
PS8502	PS8502-AX	Pb-Free (Ni/Pd/Au)	Magazine case 50 pcs	Standard products (UL, CSA, BSI, SEMKO, NEMKO, DEMKO, FIMKO approved)	PS8502
PS8502L1	PS8502L1-AX				PS8502L1
PS8502L2	PS8502L2-AX				PS8502L2
PS8502L3	PS8502L3-AX				PS8502L3
PS8502L2-E3	PS8502L2-E3-AX				PS8502L2
PS8502L3-E3	PS8502L3-E3-AX				PS8502L3
PS8502-V	PS8502-V-AX		Magazine case 50 pcs	DIN EN60747-5-2 (VDE0884 Part2) Approved (Option)	PS8502
PS8502L1-V	PS8502L1-V-AX				PS8502L1
PS8502L2-V	PS8502L2-V-AX				PS8502L2
PS8502L3-V	PS8502L3-V-AX				PS8502L3
PS8502L2-V-E3	PS8502L2-V-E3-AX				PS8502L2
PS8502L3-V-E3	PS8502L3-V-E3-AX				PS8502L3

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current ^{*1}	I _F	25	mA
	Reverse Voltage	V _R	5	V
Detector	Supply Voltage	V _{CC}	35	V
	Output Voltage	V _O	35	V
	Output Current	I _O	8	mA
	Power Dissipation ^{*2}	P _C	100	mW
Isolation Voltage ^{*3}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100	°C
Storage Temperature		T _{stg}	-55 to +125	°C

*1 Reduced to 0.33 mA/°C at T_A = 70°C or more.

*2 Reduced to 2.0 mW/°C at T_A = 75°C or more.

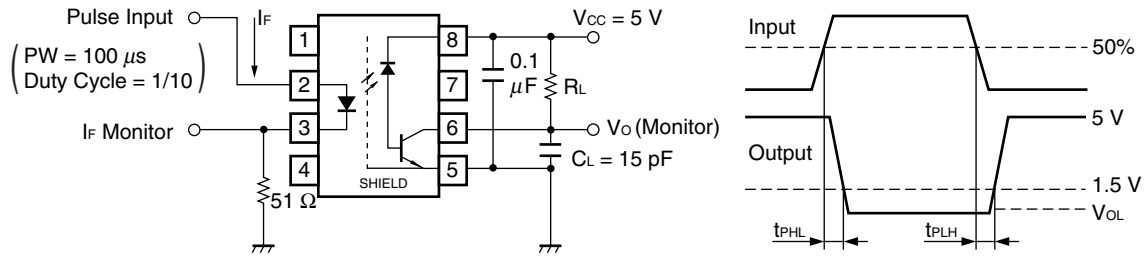
*3 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.
Pins 1-4 shorted together, 5-8 shorted together.

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP. ¹⁾	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 16 mA		1.7	2.2	V
	Reverse Current	I _R	V _R = 3 V			10	μA
	Forward Voltage Temperature Coefficient	ΔV _F /ΔT _A	I _F = 16 mA		-2.1		mV/°C
	Terminal Capacitance	C _i	V = 0 V, f = 1 MHz		60		pF
Detector	High Level Output Current	I _{OH} (1)	I _F = 0 mA, V _{CC} = V _O = 5.5 V		3	500	nA
	High Level Output Current	I _{OH} (2)	I _F = 0 mA, V _{CC} = V _O = 35 V			100	μA
	Low Level Output Voltage	V _{OL}	I _F = 16 mA, V _{CC} = 4.5 V, I _O = 2.4 mA		0.15	0.4	V
	Low Level Supply Current	I _{CCL}	I _F = 16 mA, V _O = Open, V _{CC} = 35 V		150		μA
	High Level Supply Current	I _{CCH}	I _F = 0 mA, V _O = Open, V _{CC} = 35 V		0.01	1	μA
Coupled	Current Transfer Ratio	CTR	I _F = 16 mA, V _{CC} = 4.5 V, V _O = 0.4 V	15			%
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.7		pF
	Propagation Delay Time (H → L) ²⁾	t _{PHL}	I _F = 16 mA, V _{CC} = 5 V, R _L = 1.9 kΩ		0.22	0.8	μs
	Propagation Delay Time (L → H) ²⁾	t _{PLH}	I _F = 16 mA, V _{CC} = 5 V, R _L = 1.9 kΩ		0.35	0.8	μs
	Common Mode Transient Immunity at High Level Output ³⁾	CM _H	I _F = 0 mA, V _{CC} = 5 V, V _{CM} = 1.5 kV, R _L = 4.1 kΩ	15			kV/μs
	Common Mode Transient Immunity at Low Level Output ³⁾	CM _L	I _F = 16 mA, V _{CC} = 5 V, V _{CM} = 1.5 kV, R _L = 4.1 kΩ	-15			kV/μs

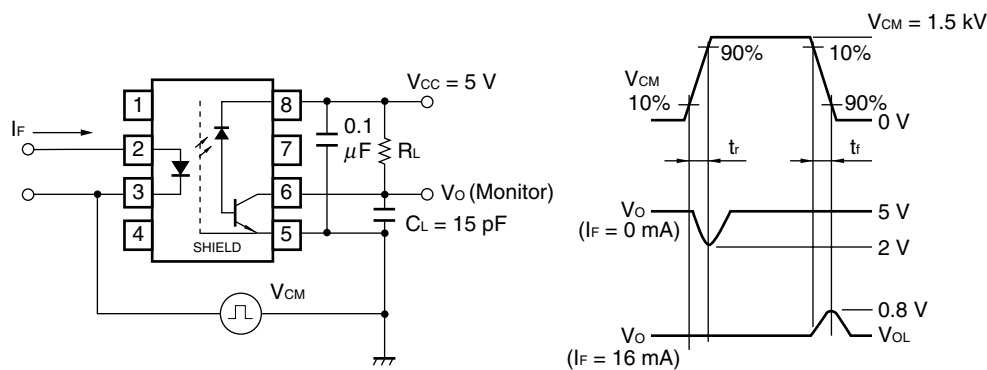
*1 Typical values at $T_A = 25^\circ\text{C}$

*2 Test circuit for propagation delay time



Remark C_L includes probe and stray wiring capacitance.

*3 Test circuit for common mode transient immunity



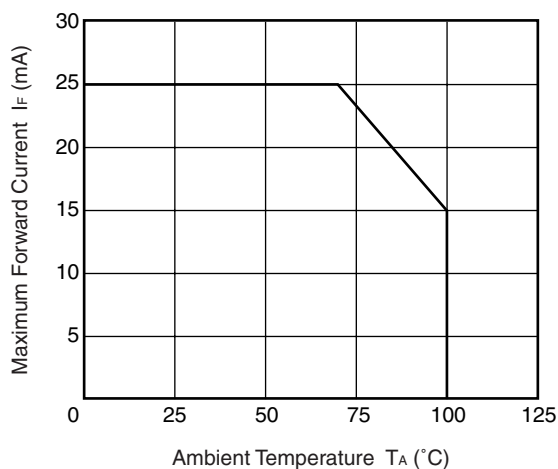
Remark C_L includes probe and stray wiring capacitance.

USAGE CAUTIONS

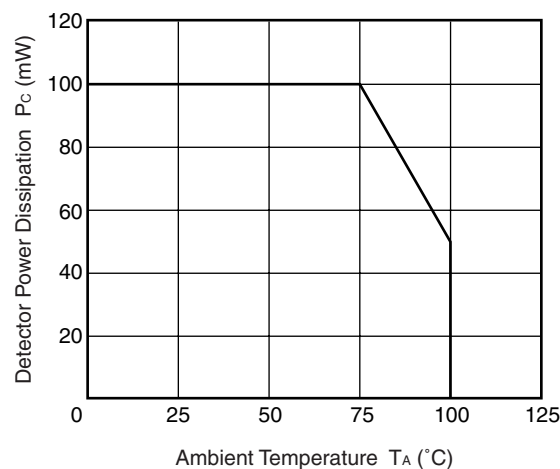
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than $0.1\ \mu\text{F}$ is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Avoid storage at a high temperature and high humidity.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

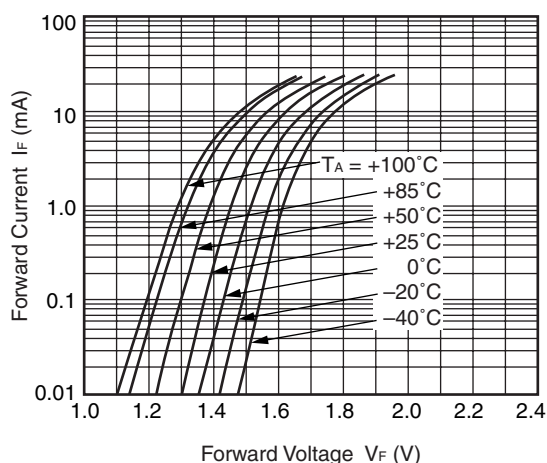
**MAXIMUM FORWARD CURRENT
vs. AMBIENT TEMPERATURE**



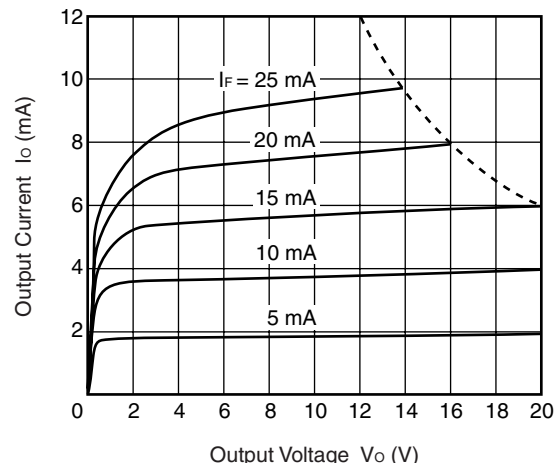
**DETECTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE**



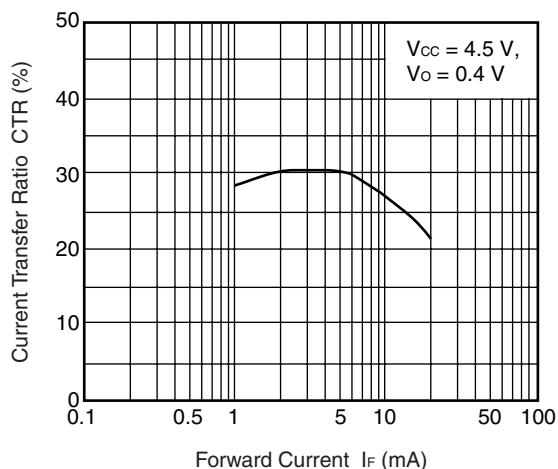
**FORWARD CURRENT vs.
FORWARD VOLTAGE**



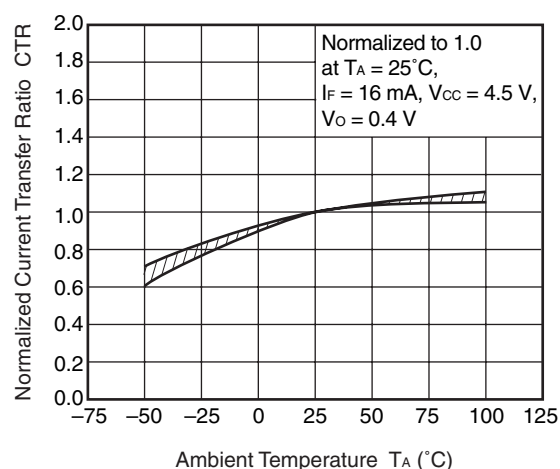
**OUTPUT CURRENT vs.
OUTPUT VOLTAGE**



**CURRENT TRANSFER RATIO
vs. FORWARD CURRENT**

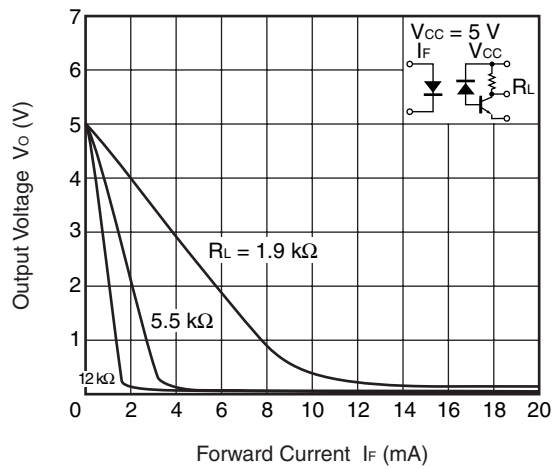


**NORMALIZED CURRENT TRANSFER
RATIO vs. AMBIENT TEMPERATURE**

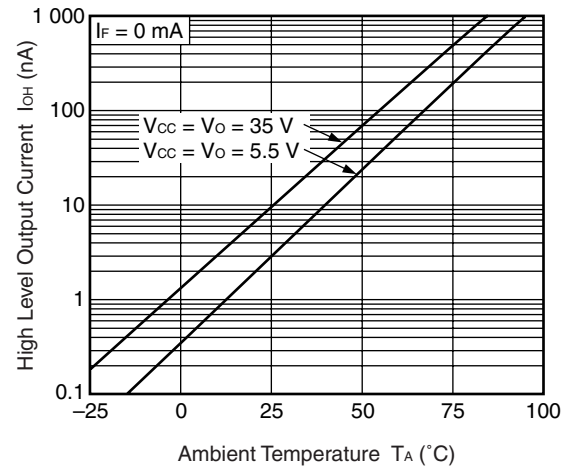


Remark The graphs indicate nominal characteristics.

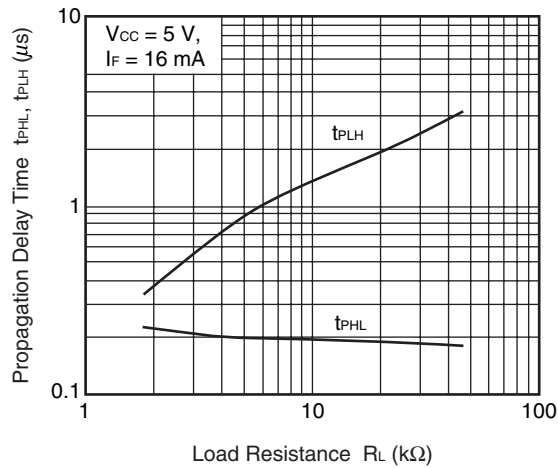
OUTPUT VOLTAGE vs.
FORWARD CURRENT



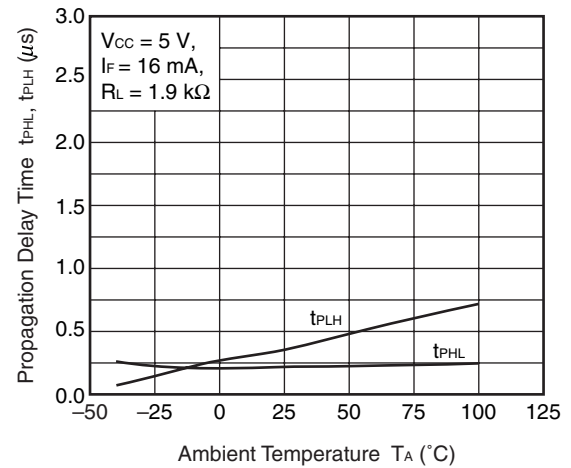
HIGH LEVEL OUTPUT CURRENT
vs. AMBIENT TEMPERATURE



PROPAGATION DELAY TIME,
vs. LOAD RESISTANCE



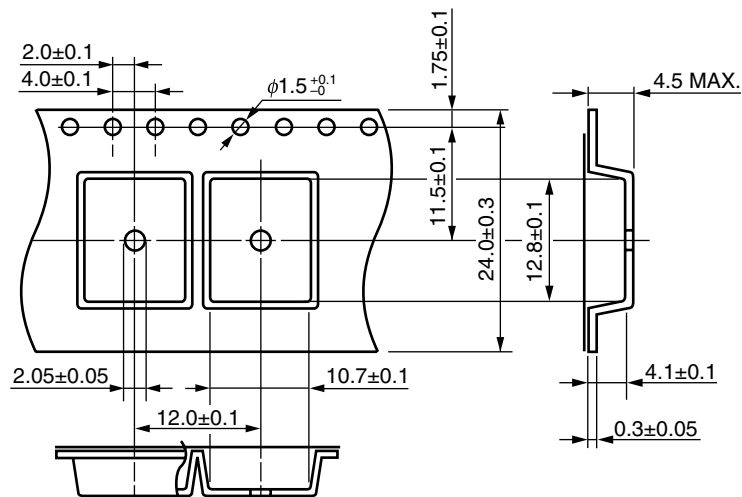
PROPAGATION DELAY TIME,
vs. AMBIENT TEMPERATURE



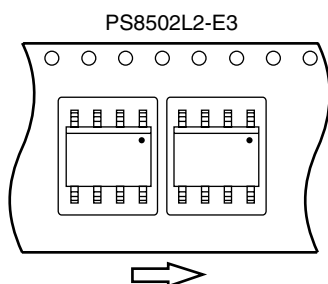
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

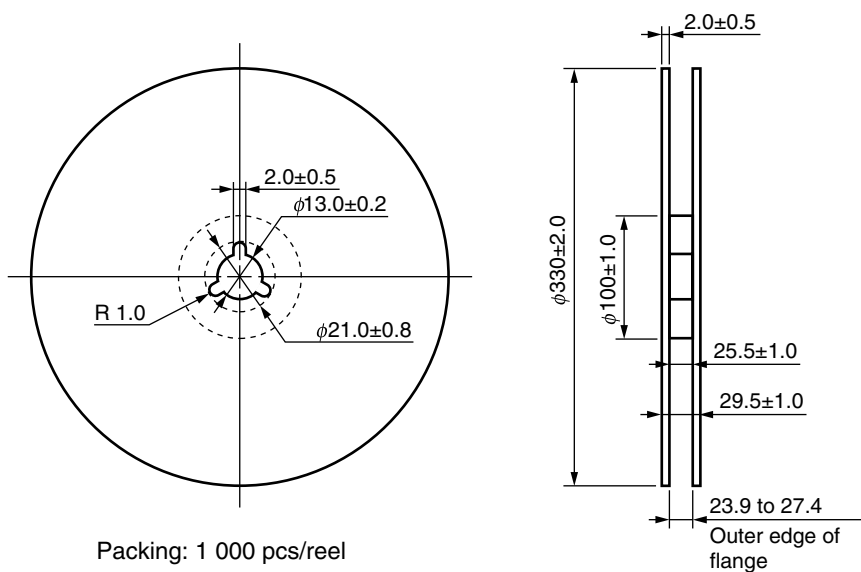
Outline and Dimensions (Tape)



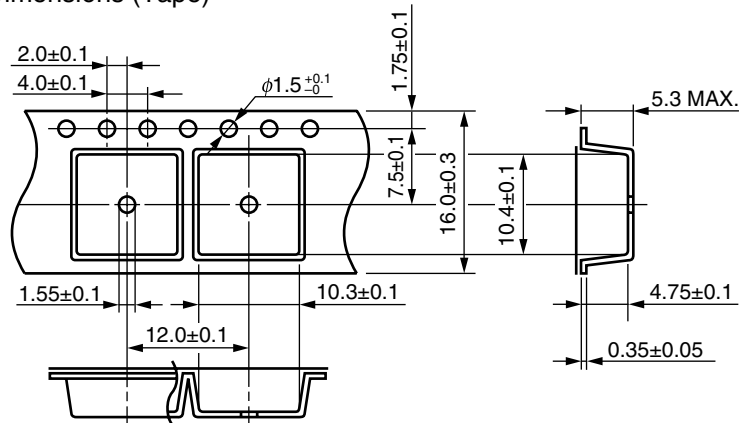
Tape Direction



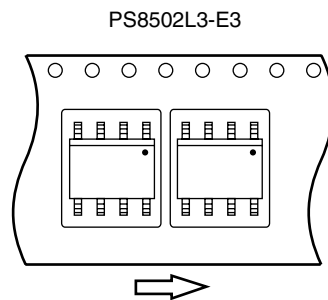
Outline and Dimensions (Reel)



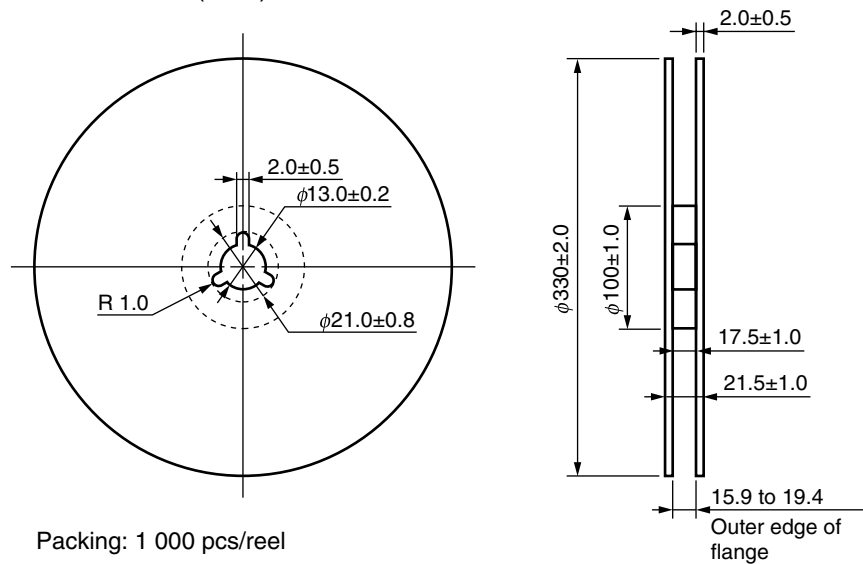
Outline and Dimensions (Tape)



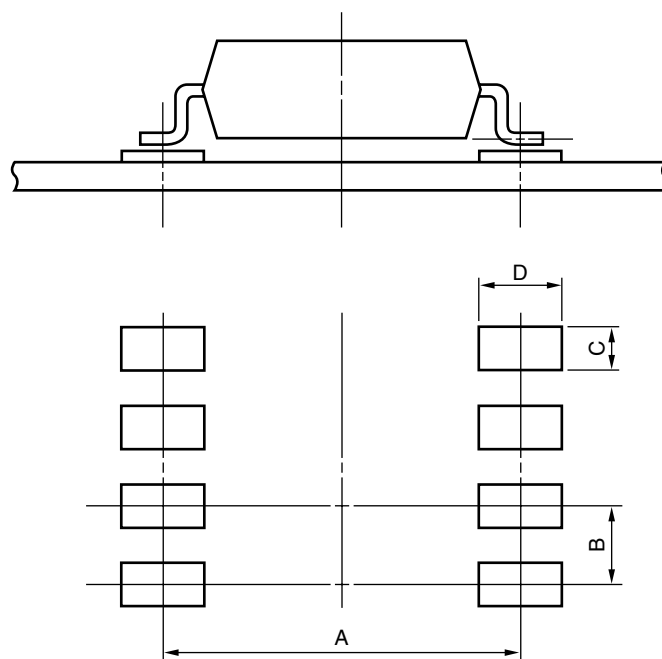
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Part Number	Lead Bending	A	B	C	D
PS8502L2	lead bending type (Gull-wing) for long creepage distance (surface mount)	10.2	2.54	1.7	2.2
PS8502L3	lead bending type (Gull-wing) for surface mount	8.2	2.54	1.7	2.2

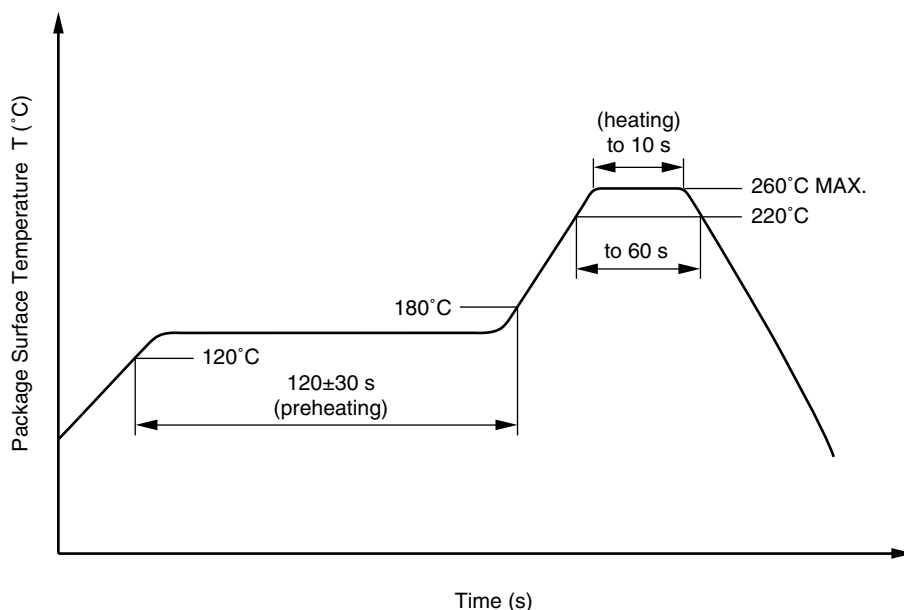
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

<R> USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Speck	Unit
Application classification (DIN EN 60664-1 VDE0110 Part 1) for rated line voltages ≤ 300 Vr.m.s. for rated line voltages ≤ 600 Vr.m.s.		IV III	
Climatic test class (DIN EN 60664-1 VDE0110)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}$, $P_d < 5$ pC	U_{IORM} U_{pr}	1 130 1 695	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5$ pC	U_{pr}	2 119	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Clearance distance		>8.0	mm
Creepage distance		>8.0	mm
Comparative tracking index (DIN IEC 112/VDE 0303 Part 1)	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +125	°C
Operating temperature range	T_A	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500$ V dc at $T_A = 25^\circ\text{C}$ $V_{IO} = 500$ V dc at T_A MAX. at least 100°C	R_{is} MIN. R_{is} MIN.	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , $P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500$ V dc at $T_A = T_{si}$	T_{si} I_{si} P_{si} R_{is} MIN.	175 400 700 10^9	°C mA mW Ω

- **The information in this document is current as of August, 2008. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.**
- No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Electronics. NEC Electronics assumes no responsibility for any errors that may appear in this document.
- NEC Electronics does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC Electronics products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC Electronics or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of a customer's equipment shall be done under the full responsibility of the customer. NEC Electronics assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
- While NEC Electronics endeavors to enhance the quality, reliability and safety of NEC Electronics products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC Electronics products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment and anti-failure features.
- NEC Electronics products are classified into the following three quality grades: "Standard", "Special" and "Specific".
 The "Specific" quality grade applies only to NEC Electronics products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of an NEC Electronics product depend on its quality grade, as indicated below. Customers must check the quality grade of each NEC Electronics product before using it in a particular application.
 "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots.
 "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).
 "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC Electronics products is "Standard" unless otherwise expressly specified in NEC Electronics data sheets or data books, etc. If customers wish to use NEC Electronics products in applications not intended by NEC Electronics, they must contact an NEC Electronics sales representative in advance to determine NEC Electronics' willingness to support a given application.

(Note)

- (1) "NEC Electronics" as used in this statement means NEC Electronics Corporation and also includes its majority-owned subsidiaries.
- (2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).

M8E 02.11-1

<div>Caution</div>	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. <ul style="list-style-type: none"> • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
--------------------	---------------	---